

***Amendments to the Specification***

Please replace the Title of the Invention with the following new title:

**Method for Making an Enhanced Die-Up Ball Grid Array Package With  
Two Substrates**

Please insert the following paragraph prior to the "Background of the Invention" section  
on page 1:

This is a divisional application of pending U.S. application Serial No.  
No.10/101,751, filed March 21, 2002 (Atty. Dkt. No. 1875.1730000), now allowed,  
which is herein incorporated by reference in its entirety.